

Polyimide Film

PMDA + ODA

Property

Polyimide film is Polyimide Polycondensate by polycondensing PMDA and ODA through the process of forming film in strong solvents and then being treated by imine at high temperature. Such film possesses excellent physical, chemical, and electrical properties, which performs successfully in the wide range of temperature as low as -452F(-269c) and as high as +436F(+260c) and can be exposed at +752F(400c) in short time, besides, it is of atomic radiation resistant. Polyimide film is currently the macromolecular compound with the best-combined properties and the highest heat resistant.



Application

1. Electric magnetic wire and cable coiling, motor slot liners, transformer interlayer insulation.
2. The backing material of pressure-sensitive adhesive tape, F46 (FEP) tapes.
3. The substrates of Flexible Printed Circuits Board (F-PCB).

Main Specification

Item	Units	Chinese Standard			Typical Values
		25,50,75	100,125	150,175	
Density	--	1.42 ±0.02			1.42 ±0.02
Tensile strength	MD	MPa	min 135		165
	CMD		min115		165
Elongation	%		min 35		60
Shrinkage	150c	%	max	1	-
	400c		max	3	-
Breakdown Strength50Hz	MV/m	min150	min 130	min110	min 170
Surface Resistivity 200c	ohm	min 1.0x10 ¹³			min 1.0x10 ¹³
Volume Resistivity 200c	ohm.m	min 1.0x10 ¹⁰			min 3.8x10 ¹⁰
Dielectric Constant 50Hz	--	3.5 ±0.4			3.2
Loss tangent 48~62Hz	--	max 4.0x10 ⁻³			max 1.8x10 ⁻³

Standard No. JB/T2726-1996

Size:

Width: 500,520,660mm, or Cutting to tapes.

Thickness (mm): 0.025, 0.05, 0.075, 0.100, 0.125, 0.150, and 0.175

Tolerance: ±10%

Min Qty: 100kgs each size in a lot.

Packing: 25--50 Kg/carton.